BERGQUIST GAP FILLER TGF 3000SF

High dispense rate, silicone-free Gap Filler

With the proliferation of sensors and optical components in multiple environments – from industrial manufacturing to semiconductor fabrication operations – the elimination of opportunities for silicone outgassing is becoming a prerequisite. At the same time, excellent thermal control, high throughput manufacturing, high reliability and cost-efficiency remain priorities for thermal interface material (TIM) selection.

Henkel's BERGQUIST GAP FILLER TGF 3000SF tackles all of these requirements, while also delivering high dielectric strength for high voltage applications. The two-part, silicone-free liquid TIM gap filler provides thermal conductivity of 3.0 W/m-K, a fast dispense rate conducive to mass production environments and high dielectric strength for outstanding electrical performance. Together, these attributes provide high reliability performance, no concerns of silicone contamination, and low stress on sensitive components in a cost-competitive formulation.

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Product	Properties	Typical value
BERGQUIST GAP FILLER TGF 3000SF	Thermal conductivity	3.0 W/m·K
	Hardness (shore 00)	70
	Viscosity (Low Shear) 1/s	Part A –500 Pa·s // Part B –500 Pa·s
	Viscosity (High Shear) 1/1500s	Part A –13 Pa·s // Part B –22 Pa·s
	Full cure	3 hours @ 85 °C
	Dielectric strength	>10 kV/mm
	Application temperature	–40 to 100 °C
	Mixing ratio	1:1

FEATURES

- Silicone-free
- High thermal conductivity > 3.0 W/m-K
- High dielectric strength > 10 kV/mm
- Fast dispense rate @ 1.5 cc/sec.
- Long working time (> 12 hours)
- Simple mixing (1:1 ratio)
- Room temperature storage
- Outstanding thermal performance up to 100° C operating temperatures

TYPICAL APPLICATIONS

- Industrial automation / power conversion (power supplies, motor drives, etc.)
- Automotive electronics (EV charging devices)
- Computers and peripherals
- Any application where silicone sensitivity is a concern

BENEFITS

- High reliability
- No outgassing interference with optical devices or mechanical contacts
- Enables design flexibility and application adaptability for product developers, affords broad deployment
- Excellent electrical performance
- High throughput
- Cost-competitive
- Reduces supply chain complexity; one material can be employed for multiple applications

CONFIGURATIONS AVAILABLE for BERGQUIST GAP FILLER TGF 3000SF

Cartridges	50 cc	200 cc	400 cc	1,200 cc
Pail Kits	7 gallons			

Reach out to our experts to partner up in solutions for thermal management.

GET IN CONTACT WITH US

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